

Special Issue

Applications of 3D Printing in Food Processing

Message from the Guest Editor

This special issue on “The application of 3D printing in Food Processing” aims to incorporate the novel advances in the 3D printing technology with the rheological behavior of printing materials. Topics include but are not limited to the following:

- Principles of 3D printing and its correlation with rheological behavior of printing materials;
- Novel technology to create materials with self-supporting mechanism during printing;
- Optimization of quality parameters involved in 3D printing operation;
- Future prospect of 3D food printing.

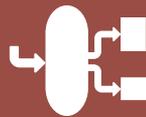
Guest Editor

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